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FDW252P

P-Channel 2.5V Specified PowerTrench® MOSFET

General Description

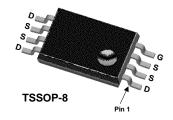
This P-Channel 2.5V specified MOSFET is a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications with a wide range of gate drive voltage (2.5V-12V).

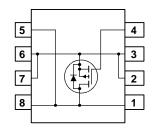
Applications

- Load switch
- Motor drive
- DC/DC conversion
- Power management

Features

- -8.8 A, -20 V. $R_{DS(ON)}$ = 0.0125 Ω @ V_{GS} = -4.5 V $R_{DS(ON)}$ = 0.018 Ω @ V_{GS} = -2.5 V
- Extended V_{GSS} range (±12V) for battery applications
- Low gate charge
- High performance trench technology for extremely low R_{DS(ON)}
- Low profile TSSOP-8 package





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain-Source Voltage		-20	V	
V _{GSS}	Gate-Source Voltage		± 12	V	
I _D	Drain Current - Continuous	(Note 1)	-8.8	Α	
	– Pulsed		-50	1	
P _D	Power Dissipation	(Note 1a)	1.3	W	
		(Note 1b)	0.6	1	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)		96	°C/W
		(Note 1b)	208	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
252P	FDW252P	13"	16mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics	,	I.		l .	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = –250 μA, Referenced to 25°C		-12		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -16 V, V _{GS} = 0 V			-1	μΑ
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = -12 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	V _{GS} = 12 V, V _{DS} = 0 V			100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.6	-0.8	-1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		3.5		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -8.8 \text{ A}$ $V_{GS} = -2.5 \text{ V}, I_D = -7.2 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -8.8 \text{ A}, T_J = 125^{\circ}\text{C}$		10 14 13	12.5 18 19	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, \qquad V_{DS} = -5 \text{ V}$	-50			Α
g _{FS}	Forward Transconductance	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -8.8 \text{ A}$		46		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance			5045		pF
Coss	Output Capacitance	$V_{DS} = -10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		1035		pF
C _{rss}	Reverse Transfer Capacitance	f = 1.0 MHz		549		pF
Switchin	ng Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time			8	16	ns
t _r	Turn-On Rise Time	$V_{DD} = -10 \text{ V}, \qquad I_{D} = -1 \text{ A},$		14	25	ns
$t_{d(off)}$	Turn-Off Delay Time	$V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		130	208	ns
t _f	Turn-Off Fall Time			80	128	ns
Q _g	Total Gate Charge			41	66	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = -10 \text{ V}, \qquad I_{D} = -8.8 \text{ A}, V_{GS} = -4.5 \text{ V}$		7		nC
Q_{gd}	Gate-Drain Charge	V _{GS} 4.5 V		11		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain–Sourc				-1.2	Α
V _{SD}	Drain–Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -1.2 A (Note 2)		-0.6	-1.2	V

Notes:

- R_{B,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface
 of the drain pins. R_{B,JC} is guaranteed by design while R_{BCA} is determined by the user's board design.
 - a) $R_{\theta JA}$ is 96°C/W (steady state) when mounted on a 1 inch² copper pad on FR-4. b) $R_{\theta JA}$ is 208°C/W (steady state) when mounted on a minimum copper pad on FR-4.
- 2. Pulse Test: Pulse Width < 300 μ s, Duty Cycle < 2.0%

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Typical Characteristics

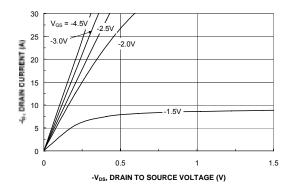


Figure 1. On-Region Characteristics.

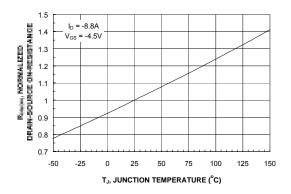


Figure 3. On-Resistance Variation with Temperature.

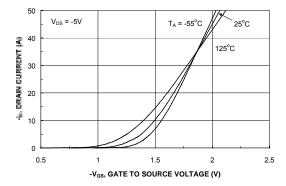


Figure 5. Transfer Characteristics.

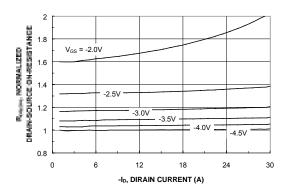


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

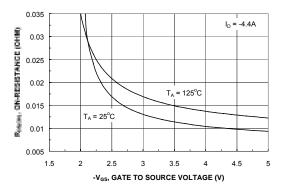


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

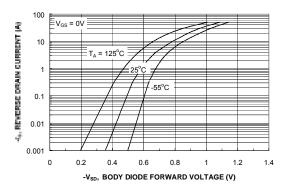
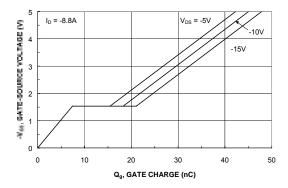


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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Typical Characteristics



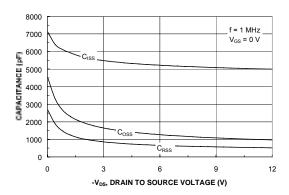
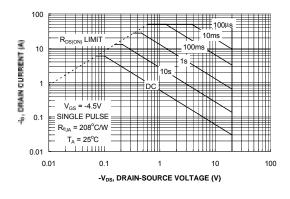


Figure 7. Gate Charge Characteristics.





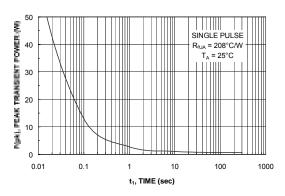


Figure 9. Maximum Safe Operating Area.



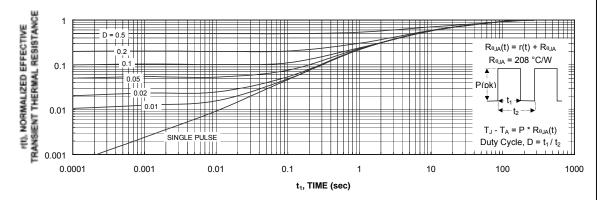


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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